

FORM PTO-1449	SERIAL NO. TBD	Siemens Ref. No. 2003P18810US (BHGL CASE NO. 12300/9)
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT (use several sheets if necessary)	FILING DATE Herewith	GROUP ART UNIT TBD
APPLICANT(S): Emery et al.		

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER <small>Number-Kind Code (if known)</small>	DATE	NAME	CLASS/ SUBCLASS	FILING DATE
	A1	4,567,895	02/04/86	Putzke	128/660	04/02/84
	A2	5,545,942	08/13/96	Jaster et al.	310/341	11/21/94
	A3	5,560,362	10/01/96	Sliwa, Jr., et al.	128/660.03	06/13/94
	A4	5,690,114	11/25/97	Chiang et al.	128/661.01	02/12/96
	A5	5,721,463	02/24/98	Snyder	310/334	12/29/95
	A6	5,882,310	03/16/99	Marian, Jr.	600/459	12/01/97
	A7	5,961,465	10/05/99	Kelly, Jr. et al.	600/459	02/10/98
	A8	6,050,943	04/18/00	Slayton et al.	600/439	10/14/97
	A9	6,142,947	11/07/00	Tran et al.	600/459	12/04/98
	A10	6,433,464 B2	08/13/02	Jones	310/328	08/31/01
	A11	6,605,043 B1	08/12/03	Dreschel et al.	600/459	12/30/98
	A12	6,669,638 B1	12/30/03	Miller et al.	600/438	10/10/02

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER <small>Number-Kind Code (if known)</small>	DATE	COUNTRY	CLASS/ SUBCLASS	TRANSLATION YES OR NO

EXAMINER INITIAL	OTHER ART - NON PATENT LITERATURE DOCUMENTS (Include name of author, title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date page(s), volume-issue number(s), publisher, city and/or country where published.	
	A13	Robert E. Simons, electronics cooling applications article "Electronics Cooling: Direct liquid immersion cooling for high power density microelectronics" obtained at http://www.electronics-cooling.com/Resources/EC_Articles/May96/may96_04.htm , pp. 1-9, 2/13/04

EXAMINER /Crystal Leach/	DATE CONSIDERED 06/17/2008
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.